

RFM18N08, RFM18N10, RFP18N08, RFP18N10

File Number 1446

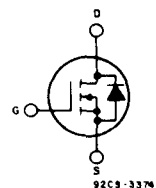
N-Channel Enhancement-Mode
Power Field-Effect Transistors

18 A, 80 V — 100 V

 $r_{DS(on)}$: 0.1 Ω

Features:

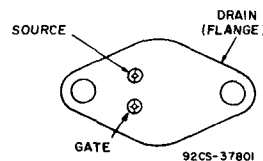
- SDA is power-dissipation limited
- Nanosecond switching speeds
- Linear transfer characteristics
- High input impedance
- Majority carrier device



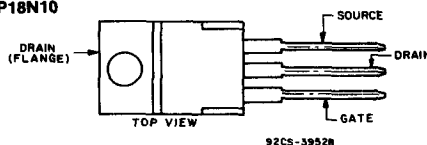
N-Channel Enhancement Mode

RFM18N08
RFM18N10

TERMINAL DESIGNATIONS



JEDEC TO-204AA

RFP18N08
RFP18N10

JEDEC TO-220AB

The RFM18N08 and RFM18N10 and the RFP18N08 and RFP18N10* are n-channel enhancement-mode silicon-gate power field-effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers, and drivers for high-power bipolar switching transistors requiring high speed and low gate-drive power. These types can be operated directly from integrated circuits.

The RFM-series types are supplied in the JEDEC TO-204AA steel package and the RFP-series types in the JEDEC TO-220AB plastic package.

*The RFM and RFP series were formerly RCA developmental numbers TA9286 and TA9287, respectively.

MAXIMUM RATINGS, Absolute-Maximum Values ($T_c=25^\circ\text{C}$):

		RFM18N08	RFM18N10		RFP18N08	RFP18N10	
DRAIN-SOURCE VOLTAGE	V_{DS}	80	100		80	100	V
DRAIN-GATE VOLTAGE ($R_{GS}=1\text{ M}\Omega$)	V_{DGR}	80	100		80	100	V
GATE-SOURCE VOLTAGE	V_{GS}	± 20			± 20		V
DRAIN CURRENT RMS Continuous	I_D	18			18		A
Pulsed	I_{DM}	45			45		A
POWER DISSIPATION							
@ $T_c=25^\circ\text{C}$	P_T	100	100		75	75	W
Derate above $T_c=25^\circ\text{C}$		0.8	0.8		0.6	0.6	W/ $^\circ\text{C}$
OPERATING AND STORAGE TEMPERATURE	T_j, T_{stg}	-55 to +150			-55 to +150		$^\circ\text{C}$

RFM18N08, RFM18N10, RFP18N08, RFP18N10**ELECTRICAL CHARACTERISTICS** At Case Temperature (T_c) = 25° C unless otherwise specified

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	LIMITS				UNITS
			RFM18N08 RFP18N08		RFM18N10 RFP18N10		
			MIN.	MAX.	MIN.	MAX.	
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D = 1\text{ mA}$ $V_{GS} = 0$	80	—	100	—	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS} = V_{DS}$ $I_D = 1\text{ mA}$	2	4	2	4	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 65\text{ V}$	—	1	—	—	μA
		$V_{DS} = 80\text{ V}$	—	—	—	1	
		$T_C = 125^\circ\text{ C}$ $V_{DS} = 65\text{ V}$	—	50	—	—	
		$V_{DS} = 80\text{ V}$	—	—	—	50	
Gate-Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20\text{ V}$ $V_{DS} = 0$	—	100	—	100	nA
Drain-Source On Voltage	$V_{DS(on)}^*$	$I_D = 9\text{ A}$ $V_{GS} = 10\text{ V}$	—	1.08	—	1.08	V
		$I_D = 18\text{ A}$ $V_{GS} = 10\text{ V}$	—	3.0	—	3.0	
Static Drain-Source On Resistance	$r_{DS(on)}^*$	$I_D = 9\text{ A}$ $V_{GS} = 10\text{ V}$	—	0.10	—	0.10	Ω
Forward Transconductance	g_{fs}^*	$V_{DS} = 10\text{ V}$ $I_D = 9\text{ A}$	5	—	5	—	mho
Input Capacitance	C_{iss}	$V_{DS} = 25\text{ V}$	—	1700	—	1700	pF
Output Capacitance	C_{oss}	$V_{GS} = 0\text{ V}$	—	750	—	750	
Reverse Transfer Capacitance	C_{rss}	$f = 1\text{MHz}$	—	300	—	300	
Turn-On Delay Time	$t_d(on)$	$V_{DD}=50\text{ V}$	60(typ.)	90	60(typ.)	90	ns
Rise Time	t_r	$I_D = 9\text{ A}$	300(typ.)	450	300(typ.)	450	
Turn-Off Delay Time	$t_d(off)$	$R_{gen} = R_{gs} = 50\ \Omega$	150(typ.)	225	150(typ.)	225	
Fall Time	t_f	$V_{GS} = 10\text{ V}$	150(typ.)	225	150(typ.)	225	
Thermal Resistance Junction-to-Case	$R\theta_{JC}$	RFM18N08, RFM18N10	—	1.25	—	1.25	$^\circ\text{C/W}$
		RFP18N08, RFP18N10	—	1.67	—	1.67	

*Pulsed: Pulse duration = 300 μs max., duty cycle = 2%.**SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS**

CHARACTERISTIC	SYMBOL	TEST CONDITIONS	LIMITS				UNITS
			RFM18N08 RFM18N10		RFP18N08 RFP18N10		
			MIN.	MAX.	MIN.	MAX.	
Diode Forward Voltage	V _{SD}	I _{SD} =9 A	—	1.4	—	1.4	V
Reverse Recovery Time	t _{rr}	I _F =4 A dI _F /d _t =100 A/μs	150(typ)		150(typ)		ns

*Pulse Test: Width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$

RFM18N08, RFM18N10, RFP18N08, RFP18N10

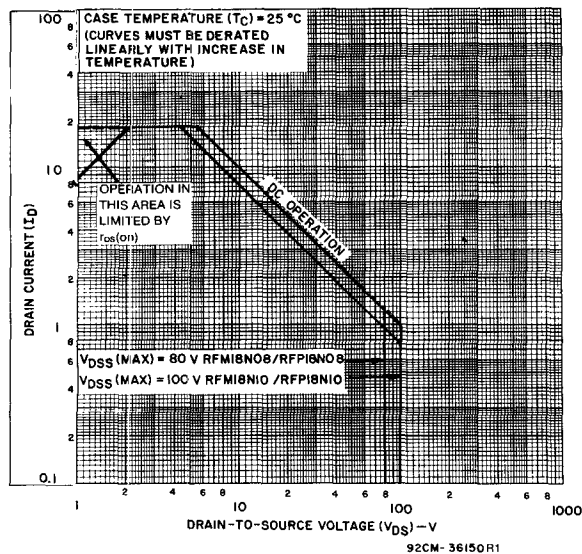


Fig. 1 — Maximum operating areas for all types.

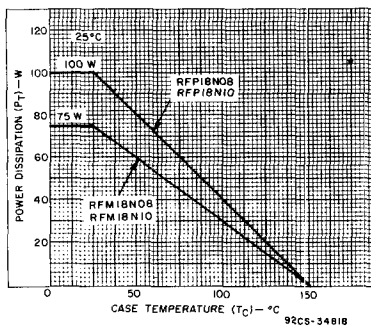


Fig. 2 — Power dissipation vs. case temperature derating curve for all types.

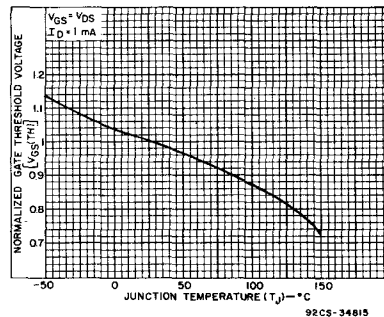


Fig. 3 — Typical normalized gate threshold voltage as a function of junction temperature for all types.

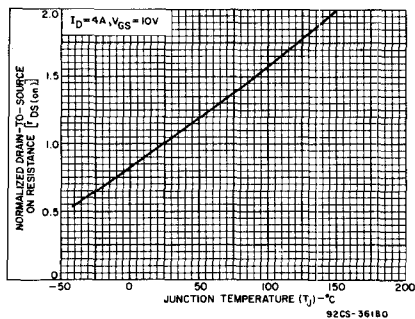


Fig. 4 — Normalized drain-to-source on resistance to junction temperature for all types.

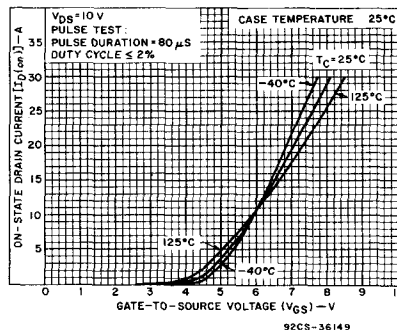


Fig. 5 — Typical transfer characteristics for all types.

RFM18N08, RFM18N10, RFP18N08, RFP18N10

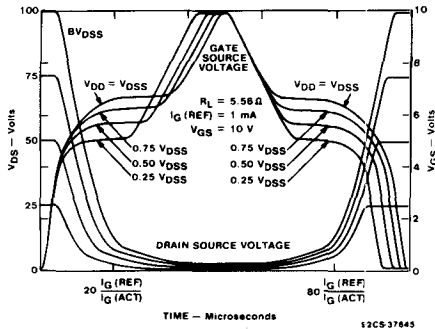


Fig. 6 - Normalized switching waveforms for constant gate-current. Refer to RCA application notes AN-7254 and AN-7260.

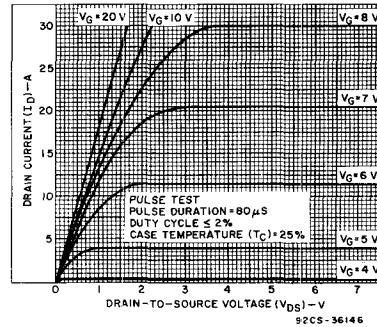


Fig. 7 - Typical saturation characteristics for all types.

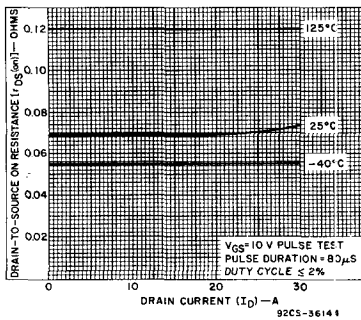


Fig. 8 - Typical drain-to-source on resistance as a function of drain current for all types.

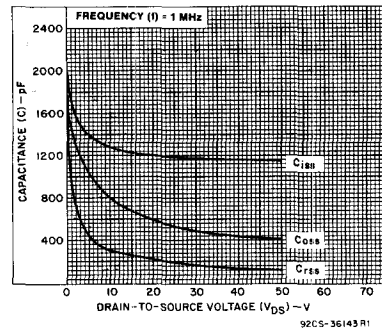


Fig. 9 - Capacitance as a function of drain-to-source voltage for all types.

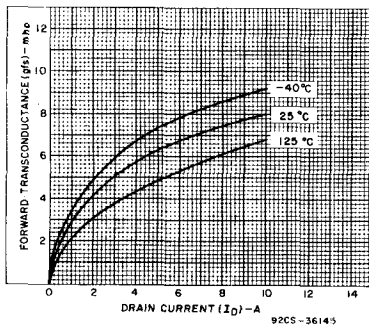


Fig. 10 - Typical forward transconductance as a function of drain current for all types.

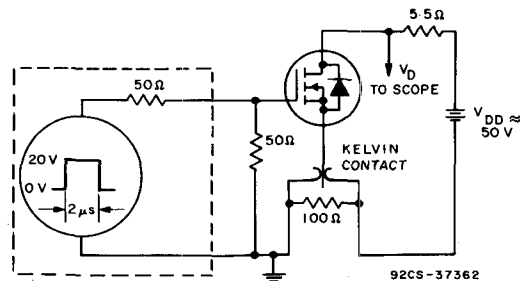


Fig. 11 - Switching Time Test Circuit